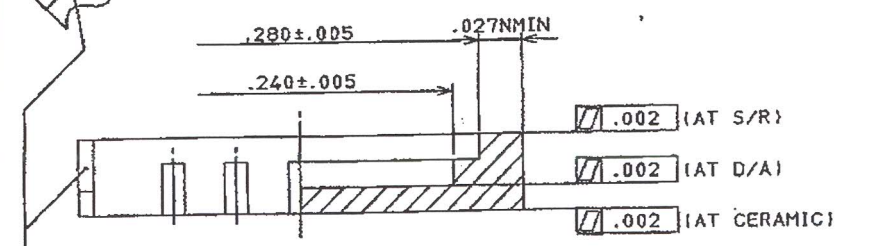
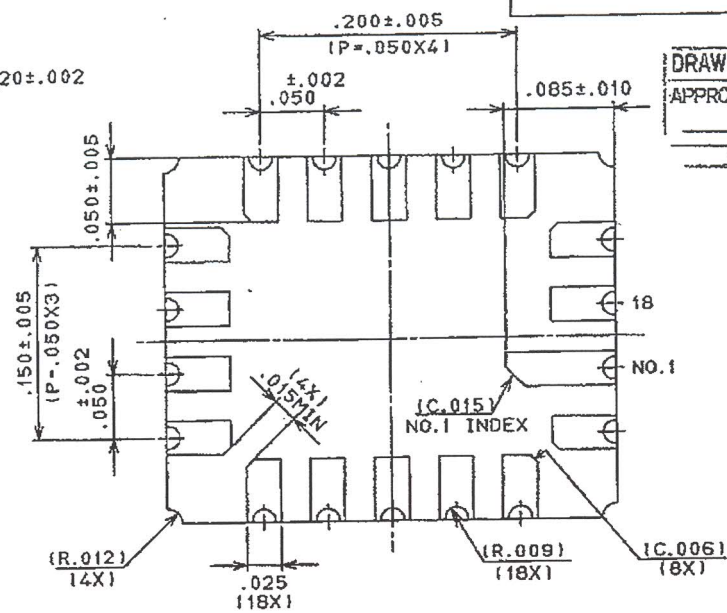
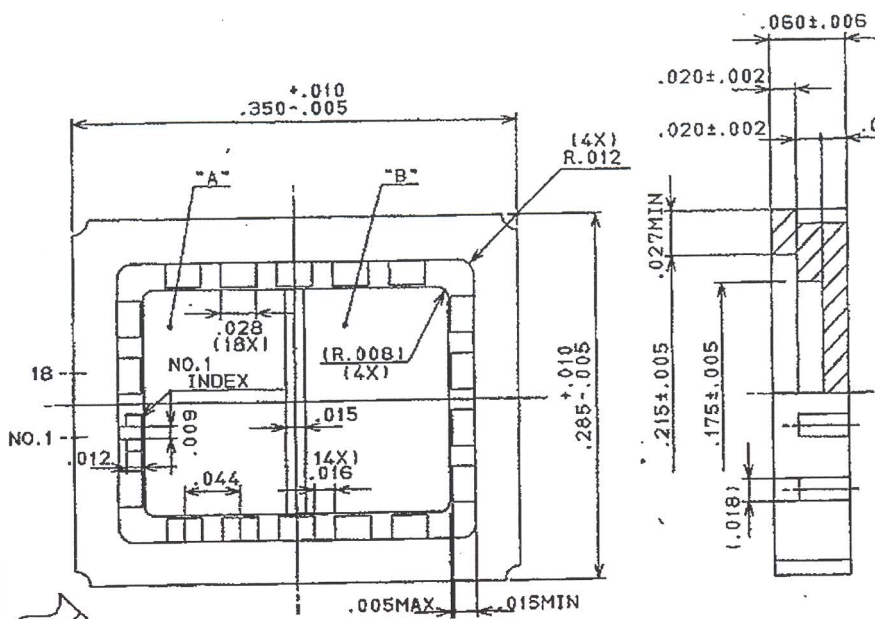


PLØ18-2417-NØ1

DRAWING FOR APPROVAL
 APPROVED BY _____
 NTK TECHNICAL CERAMIC



THIS METALLIZATION TO BE ELECTRICALLY CONNECTED TO THE SEAL RING PAD

- NOTES: 1. GOLD PLATE 60µ INCHES MIN OVER 80µ INCHES MIN NICKEL.
 2. NO LEAD TO BE ELECTRICALLY CONNECTED TO THE TWO DIE ATTACH PADS (A+B). SEAL RING ISOLATED.



MODIFIED DWG NO. _____

3				
2				
1	CERAMIC	BLACK ALUMINA		NEW DRAWING
Item Name	Material	Description	Rev.	Description
UNLESS OTHERWISE SPECIFIED TOLERANCES: ± .001				DRAWN Y. KACHI
N. L. T. & DECIMALS: .XX ± .01				CHECKED Y. KACHI
M. L. T. & DECIMALS: .XXX ± .005				TITLE
CUSTOMER	ROOD	APPROVED J. WASHINO	UNIT INCH	18LD CHIP CAF
DWG NO.		SCALE		DWG NO. IRK18F1-5045H